



SSCU3628NP30GN6

N and P-Channel Enhancement Mode Power MOSFET

➤ Features

N-Channel

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
30V	$\pm 20V$	13m Ω @10V	36A
		20m Ω @4.5V	

P-Channel

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
-30V	$\pm 20V$	22m Ω @-10V	-28A
		30m Ω @-4.5V	

➤ Description

The SSCU3628NP30GN6 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

100% UIS + ΔV_{DS} + R_g Tested!

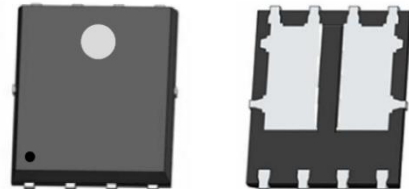
➤ Applications

- PWM Applications
- Load Switch
- DC-DC Converters
- Wireless Chargers

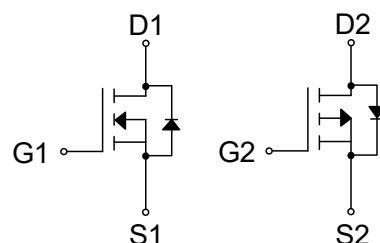
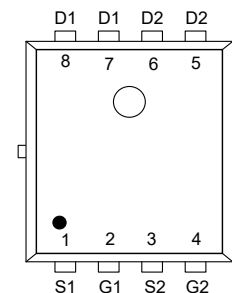
➤ Ordering Information

Device	Package	Shipping
SSCU3628NP30GN6	PDFN5X6-8L	5000/Reel

➤ Pin configuration



PDFN5X6-8L



Pin Configuration (Top View)



Marking

(XYYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter		N-Channel	P-Channel	Unit
V _{DSS}	Drain-to-Source Voltage		30	-30	V
V _{GSS}	Gate-to-Source Voltage		± 20	± 20	V
I _D	Continuous Drain Current ^d	T _C =25℃	36	-28	A
		T _C =100℃	19	-15	
I _{DSM}	Continuous Drain Current ^a	T _A =25℃	9	-7	A
		T _A =70℃	6.5	-5	
I _{DM}	Pulsed Drain Current ^b		144	-112	A
P _D	Power Dissipation ^c	T _C =25℃	45	42	W
		T _C =100℃	18	17	
P _{DSM}	Power Dissipation ^a	T _A =25℃	3	3	W
		T _A =70℃	1.9	1.9	
I _{AS}	Avalanche Current ^b L=0.5mH Single Pulse		11	-12	A
E _{AS}	Avalanche Energy ^b L=0.5mH Single Pulse		30	36	mJ
T _J	Operation junction temperature		-55~150		℃
T _{STG}	Storage temperature range		-55~150		

➤ Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Max.	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	42	53	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	2.8	4	

Note:

- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper,in a still air environment with $T_A=25^{\circ}\text{C}$.The value in any given application depends on the user is specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.



SSCU3628NP30GN6

➤ N-Channel Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250uA	30			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	1	1.6	2.2	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 8A		13	20	mΩ
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D = 6A		20	29	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30V, V _{GS} = 0V			1	uA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 8A		0.7	1.3	V
Gate Resistance	R _G	V _{DS} =0V, f=1MHz		2		Ω
Input Capacitance	C _{ISS}	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz		738		pF
Output Capacitance	C _{OSS}			85		
Reverse Transfer Capacitance	C _{RSS}			69		
Total Gate Charge	Q _G	V _{GS} = 10V, V _{DS} = 15V, I _D = 5A		16		nC
Gate to Source Charge	Q _{GS}			4.8		
Gate to Drain Charge	Q _{GD}			3.6		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 10V, V _{DS} = 15V, R _L = 1Ω, R _{GEN} = 3Ω		6		ns
Rise Time	T _r			12.5		
Turn-off Delay Time	T _{D(OFF)}			16		
Fall Time	T _f			5		
Diode Recovery Time	T _{rr}	I _F = 10A, di/dt = 100A/us		7		ns
Diode Recovery Charge	Q _{rr}			1.4		nC



SSCU3628NP30GN6

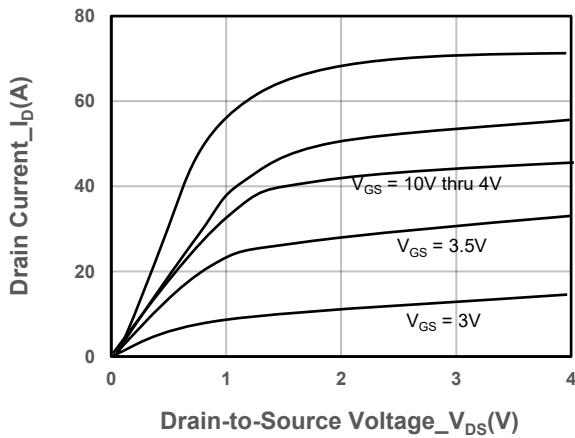
➤ P-Channel Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-30			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.7	-2.2	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = -10V, I _D = -8A		22	31	mΩ
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = -4.5V, I _D = -6A		30	50	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -30V, V _{GS} = 0V			-1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = -8A		-0.7	-1.3	V
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		11		Ω
Input Capacitance	C _{ISS}	V _{DS} = -15V, V _{GS} = 0V, f = 1MHz		871		pF
Output Capacitance	C _{OSS}			115		
Reverse Transfer Capacitance	C _{RSS}			91		
Total Gate Charge	Q _G	V _{GS} = -10V, V _{DS} = -15V, I _D = -5A		18		nC
Gate to Source Charge	Q _{GS}			3.5		
Gate to Drain Charge	Q _{GD}			4		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = -10V, V _{DS} = -15V, I _D = -5A, R _{GEN} = 3Ω		4		ns
Rise Time	T _r			2.3		
Turn-off Delay Time	T _{D(OFF)}			38		
Fall Time	T _f			25		
Diode Recovery Time	T _{rr}	I _F = -10A, di/dt = -100A/μs		10		ns
Diode Recovery Charge	Q _{rr}	I _F = -10A, di/dt = -100A/μs		3		nC

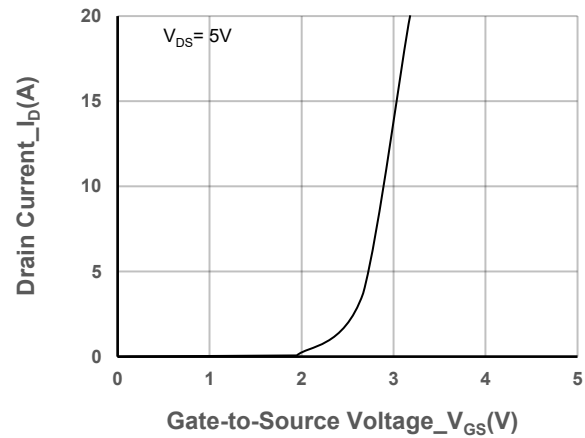


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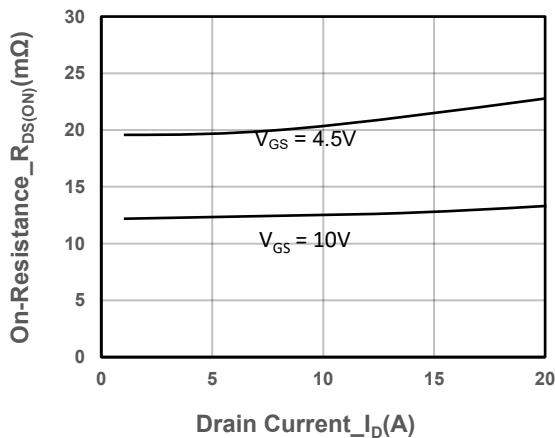
➤ N-Channel Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



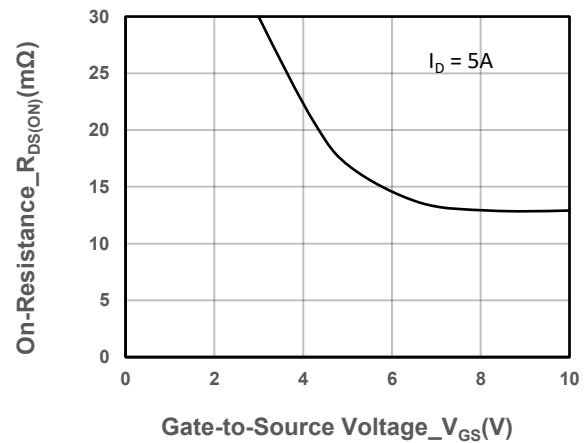
Output Characteristics



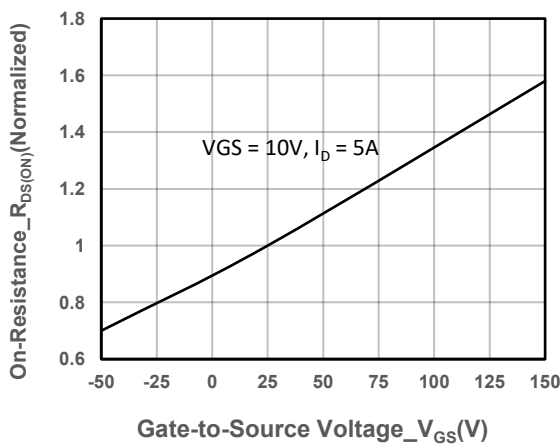
Transfer Characteristics



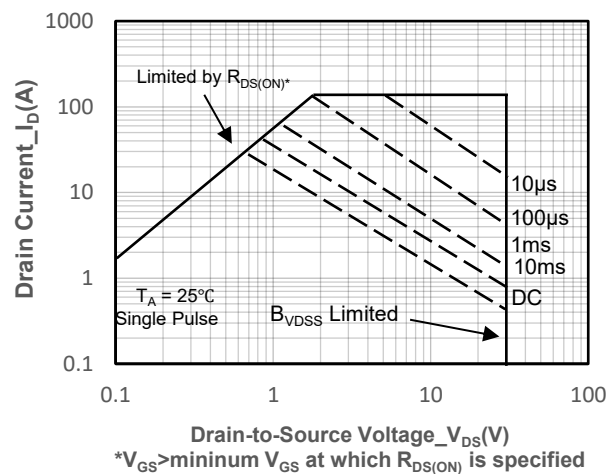
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature

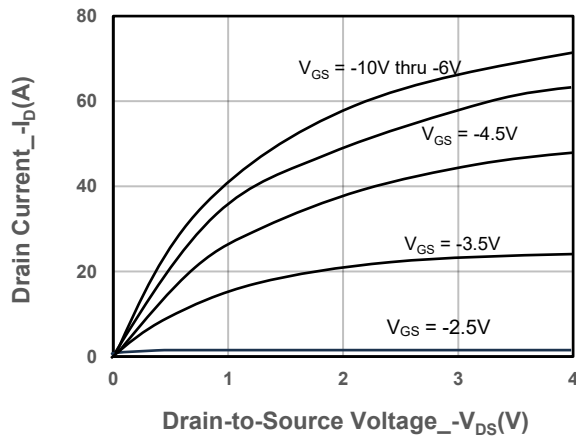


Safe Operating Area vs. Junction-to-Ambient

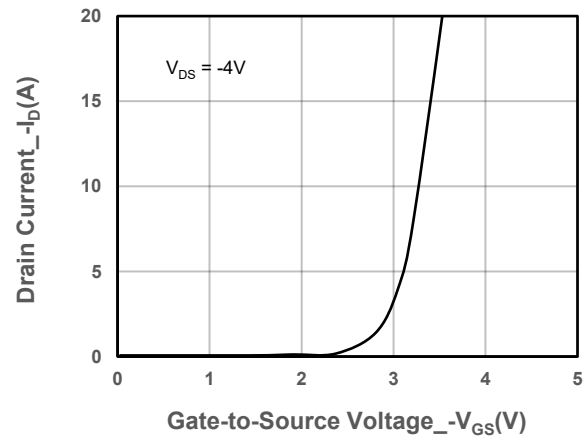


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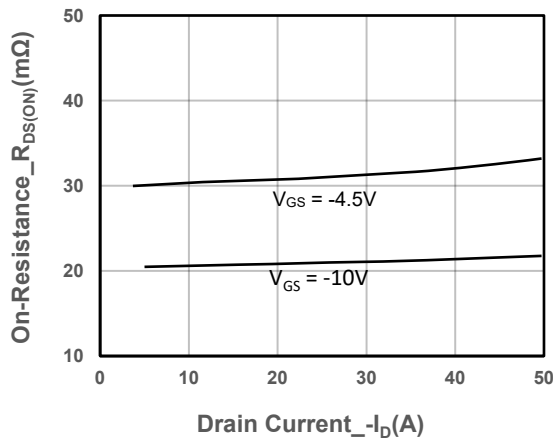
➤ P-Channel Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



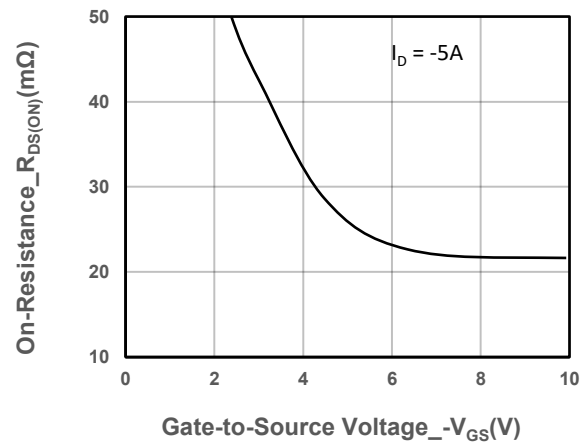
Output Characteristics



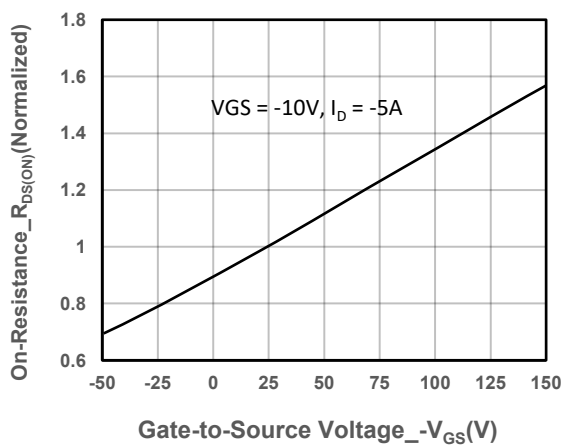
Transfer Characteristics



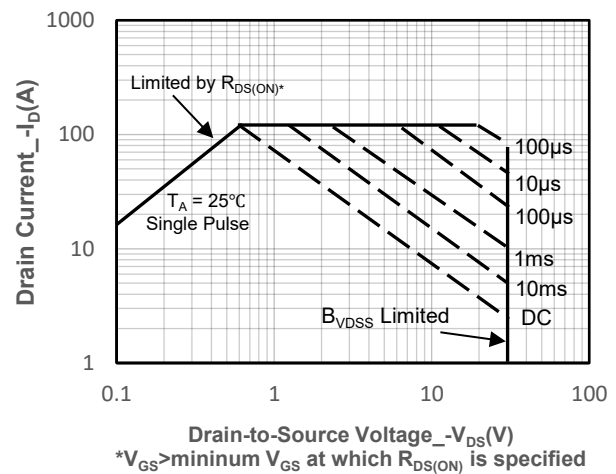
On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage



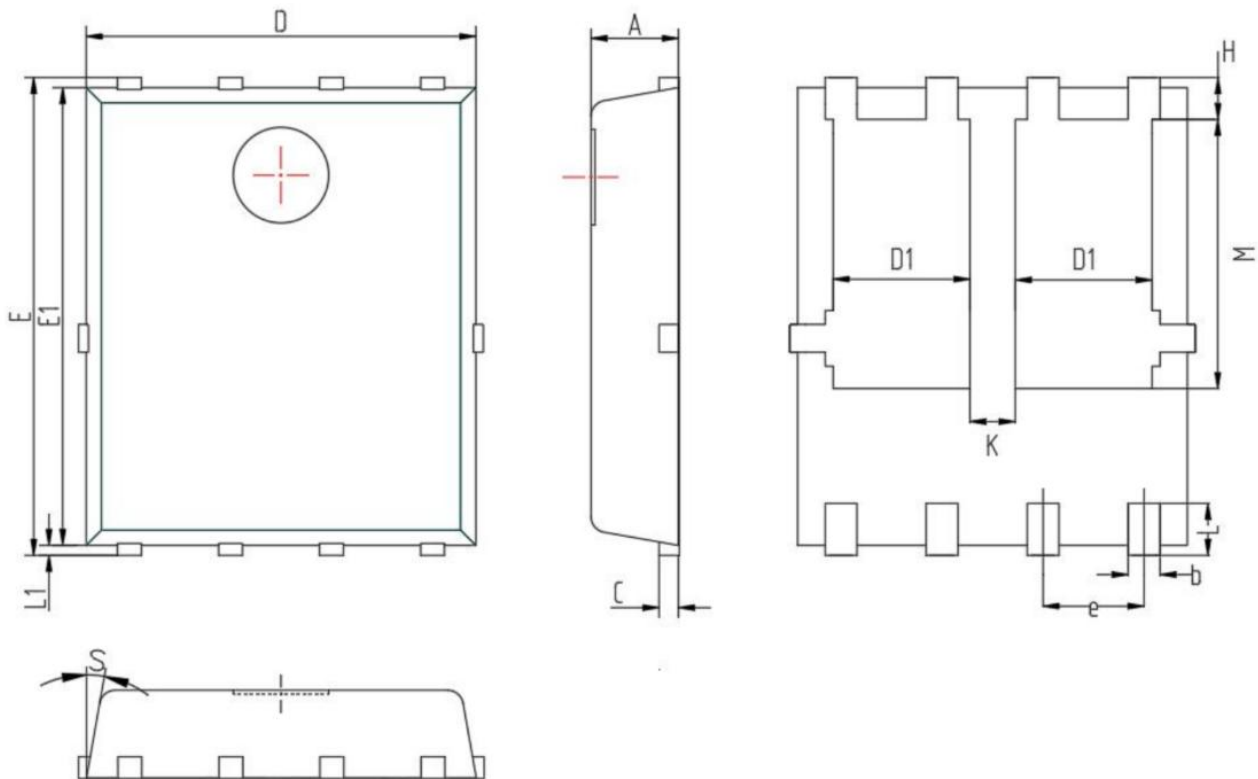
On-Resistance vs. Junction Temperature



Safe Operating Area vs. Junction-to-Ambient



➤ Package Information



Symbol	MILL IMETER		
	Min	Nom	Max
A	0.9	1.10	1.20
b	0.25	0.30	0.5
C	0.20	0.25	0.35
D	4.80	5.00	5.20
D1	1.50	1.70	1.80
E	5.90	6.00	6.30
E1	5.60	5.75	5.90
e	1.27BSC		
H	0.48	0.58	0.80
K	0.50	0.60	0.70
L	0.50	0.60	0.84
L1	0.10	0.15	0.30
M	3.30	3.48	3.67
S	12° BSC		



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